

D SUB FE SMT LOW PROFILE ANGLED 9P PL3 W



Image is for illustration purposes only. Please refer to product description.

Identification

Category	Connectors
Series	D-Sub
Identification	Standard
Element	Connector
Specification	Low-profile
Description of the contact	Stamped Angled

Version

Termination method	Reflow soldering termination (SMT)
Gender	Female
Size	D-Sub 1
Connection type	Motherboard to daughtercard
Number of contacts	9
Locking type	Fixing flange with fitted screw lock M3
Pack contents	160 pieces on reel

Technical characteristics

Distance between rows	2.84 mm
Contact spacing (termination side)	2.76 mm
Rated current	5 A
Clearance distance	≥1 mm
Creepage distance	≥1 mm

Technical characteristics

Insulation resistance	> 5 x 10 ⁹ Ω
Contact resistance	≤25 mΩ
Tightening torque	≤0.4 Nm Locking screw
Limiting temperature	-55 ... +125 °C (during reflow soldering max. +240 °C for 30 s)
Insertion force	≤30 N
Withdrawal force	≥3.3 N ≤20 N
Performance level	3
Mating cycles	≥50
Test voltage U _{r.m.s.}	1 kV
Isolation group	IIIa (175 ≤ CTI < 400)
PCB thickness	≥1.6 mm
Installation height	3.6 mm
Hot plugging	No
Moisture Sensitivity Level (MSL)	1 acc. to ECA/IPC/JEDEC J-STD-020D
Process Sensitivity Level (PSL)	R0 acc. to ECA/IPC/JEDEC J-STD-020D

Material properties

Material (insert)	Liquid crystal polymer (LCP) Shell: steel, nickel plated
Colour (insert)	Black
Material (contacts)	Copper alloy Ground: Zinc die-cast
Surface (contacts)	Noble metal over Ni
Material flammability class acc. to UL 94	V-0

Specifications and approvals

Specifications	DIN 41652
UL / CSA	UL 1977 ECBT2.E102079

Commercial data

Packaging size	1
Net weight	1,800 g
Country of origin	China
European customs tariff number	85366990



Pushing Performance

Since 1945

Commercial data

GTIN	5713140878914
ETIM	EC001136
eCl@ss	27440214 D-Sub coupler